



Product Change Notification

110468 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 110468 - 00
Change Title: Tower Heat-Sink FXXRGTHSINK, 2 Pack, PCN 110468-00, Product Design, Package Update
Date of Publication: February 18, 2011

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Mar 4, 2011
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Description of Change to the Customer:

A package change is being made to the tower heat-sink FXXRGTSINK:

The FXXRGTHSINK (MM#901335, has 2 Special tower heat sinks required for the Intel® Server Chassis SC5600LX, the 2 heat sinks ship in a single package and the Minimum Order Quantity is 2) is being discontinued and will be replaced with a new product code FXXRGTHS (MM#904992). The FXXRGTHS will still contain 2 of the same special tower heat sinks required for the Intel® Server Chassis SC5600LX, but each heat sink is individually packaged and labeled. The MOQ (Minimum Order Quantity) still remains 2.

Customer Impact of Change and Recommended Action:

Intel does not foresee any adverse customer impact from these changes.

Products Affected / Intel Ordering Codes:

Pre Conversion Product Code	Pre Conversion MM#	Post Conversion Product Code	Post Conversion MM#
FXXRGTHSINK	901335	FXXRGTHS	904992

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
February 11, 2011	00	Originally Published PCN